molex



Part Number : 760455001
Product Description : Small Form-factor Pluggable Plus (SFP+) Stacked 2-by-2 Multi-Port Connector with 4 Lightpipe Ports, EMI Metal Gasket, 80 Circuits, Tin (Sn) Tails
Series Number : 76045
Status : Active
Product Category : High-Speed I/O Connectors

Documents and Resources

Drawings

760455001_sd.pdf

3006409058-000.pdf

3D Models and Design Files

STEP AP242

SOLIDWORKS

Creo

3006409058-000.zip

EE-76090-001-001.pdf

SP-76090-001-001.zip

Specifications

AS-75310-001-001.pdf

AS-76090-001-001.pdf

PK-75714-001-001.pdf

PS-75310-001-001.pdf

TS-76092-999-001.pdf

Tooling Specifications

3006409058-000.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant

China RoHS	per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)7771-DC (04 Feb 2026)
EU RoHS	Compliant per EU 2015/863

Compliance Statements
- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents
- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest
- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	76045
Description	Small Form-factor Pluggable Plus (SFP+) Stacked 2-by-2 Multi-Port Connector with 4 Lightpipe Ports, EMI Metal Gasket, 80 Circuits, Tin (Sn) Tails
Application	Module-to-Board
Component Type	Receptacle
Product Name	SFP Plus,SFP+
Type	Pluggable
UPC	800756878089

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Data Rate	10.0 Gbps, 28.0 Gbps
Grounding to Panel	None
Shielded	Yes
Shield Type	EMI Gasket
Voltage - Maximum	120V AC (RMS)/DC

Physical

Boot Color	N/A
Circuits Detail	80
Circuits (Loaded)	80
Circuits (maximum)	80
Color - Resin	Black, Clear (Blue Tint)
Durability (mating cycles max)	100
Flammability	94V-0
Gender	Female
Keying to Mating Part	No
Lock to Mating Part	Yes
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic, Polycarbonate
Net Weight	50.387/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	No
PCB Locator	Yes
PCB Retention	Yes

PCB Thickness - Recommended	1.57mm
PC Tail Length	2.07mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	4
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin
Waterproof / Dustproof	No

Solder Process Data

Lead-Free Process Capability	N/A

Application Tooling